

N-Channel Enhancement Mode Power MOSFET

Description

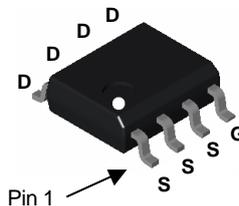
The uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

General Features

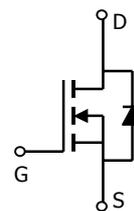
PRODUCT SUMMARY		
V_{DSS}	I_D	$R_{DS(on)}$ (m Ω) Max
30V	10 A	13.5 @ $V_{GS} = 10V$
	5 A	18.0 @ $V_{GS} = 4.5V$

- High power and current handing capability
- Lead free product is acquired
- Surface mount package

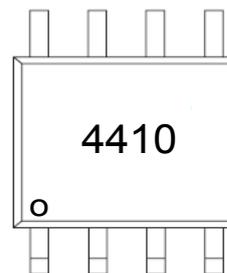
SOP-8L



Equivalent Circuit



MARKING



Y :year code W :week code

Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted				
Parameter	Symbol	Maximum	Units	
Drain-Source Voltage	V_{DS}	30	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Continuous Drain Current ^A	$T_A=25^\circ C$	I_D	10	A
Pulsed Drain Current ^B		I_{DM}	45	
Power Dissipation ^A	$T_A=25^\circ C$	P_D	2.3	W
	$T_A=70^\circ C$		1.6	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$	

Thermal Characteristics					
Parameter	Symbol	Typ	Max	Units	
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	48	62.5	t $\leq 10s$	
Maximum Junction-to-Ambient ^A				Steady-State	
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	35	40	Steady-State	

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24V, V _{GS} = 0V			500	nA
I _{GSS}	Gate-Body leakage current	V _{DS} = 0V, V _{GS} = ±20V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1.0	1.6	2.5	V
I _{D(ON)}	On state drain current	V _{GS} = 10V, V _{DS} = 5V			45	A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 10A		11	13.5	mΩ
		V _{GS} = 4.5V, I _D = 5A		16	18.0	mΩ
g _{FS}	Forward Transconductance	V _{DS} = 15V, I _D = 10A		9		S
V _{SD}	Diode Forward Voltage	I _S = 3A, V _{GS} = 0V		0.8	1.2	V
I _S	Maximum Body-Diode Continuous Current				3	A

DYNAMIC PARAMETERS

C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz		710		pF
C _{oss}	Output Capacitance			155		pF
C _{rss}	Reverse Transfer Capacitance			145		pF
R _g	Gate resistance	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz			3.0	Ω

SWITCHING PARAMETERS

Q _g (10V)	Total Gate Charge (10V)	V _{DD} = 20V, V _{GEN} = 10V, I _D = 9A		8		nC
Q _g (4.5V)	Total Gate Charge (4.5V)			6.2		nC
Q _{gs}	Gate Source Charge			3.3		nC
Q _{gd}	Gate Drain Charge			2.7		nC
t _{D(on)}	Turn-On DelayTime	V _{DD} = 15V, V _{GEN} = 10V, R _L = 15Ω R _{GEN} = 3Ω, I _D = 9A		7.0		ns
t _r	Turn-On Rise Time			7.0		ns
t _{D(off)}	Turn-Off DelayTime			22		ns
t _f	Turn-Off Fall Time			7.0		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F = 10A, di/dt = 100A/μs		24		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F = 10A, di/dt = 100A/μs		14		nC

A: The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A = 25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t_s ≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

D: The static characteristics in Figures 1 to 6, 12, 14 are obtained using 80μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A = 25°C. The SOA curve provides a single pulse rating.

Characteristics Curve

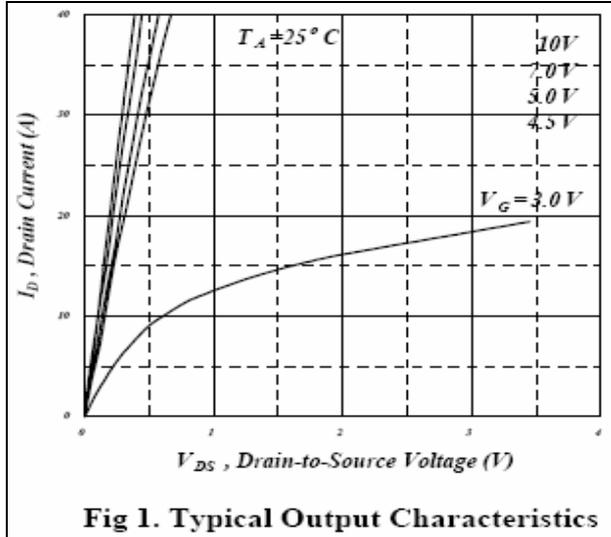


Fig 1. Typical Output Characteristics

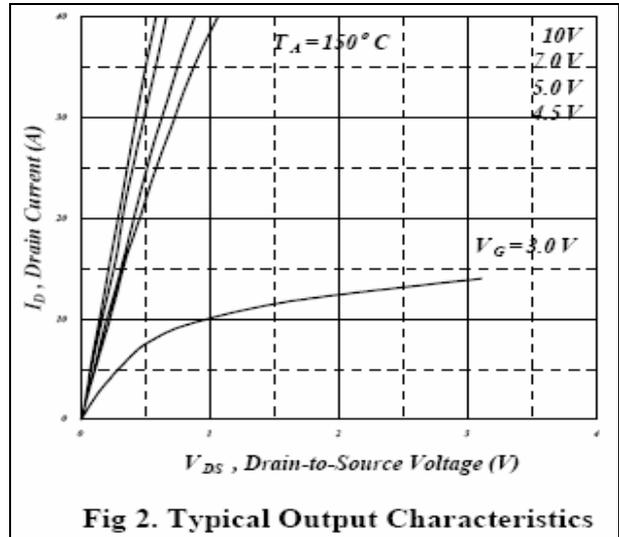


Fig 2. Typical Output Characteristics

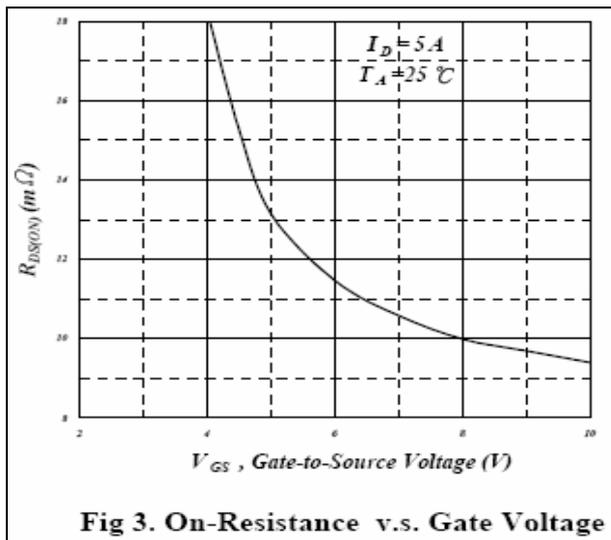


Fig 3. On-Resistance v.s. Gate Voltage

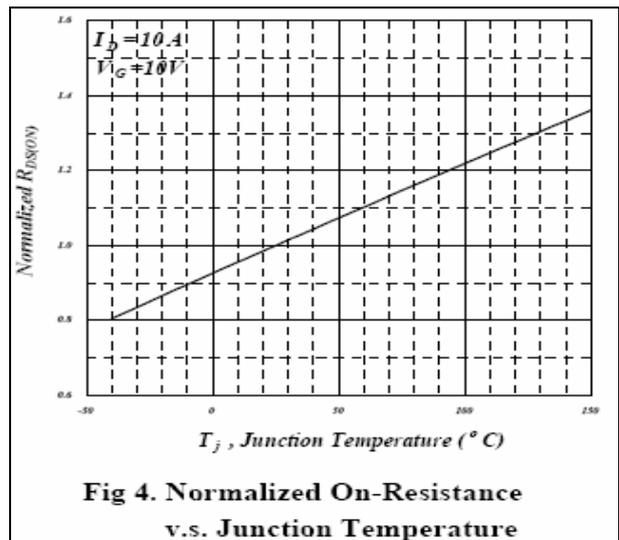


Fig 4. Normalized On-Resistance v.s. Junction Temperature

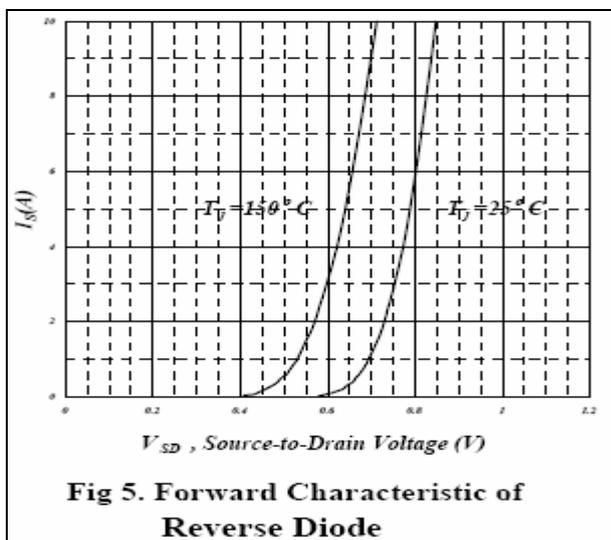


Fig 5. Forward Characteristic of Reverse Diode

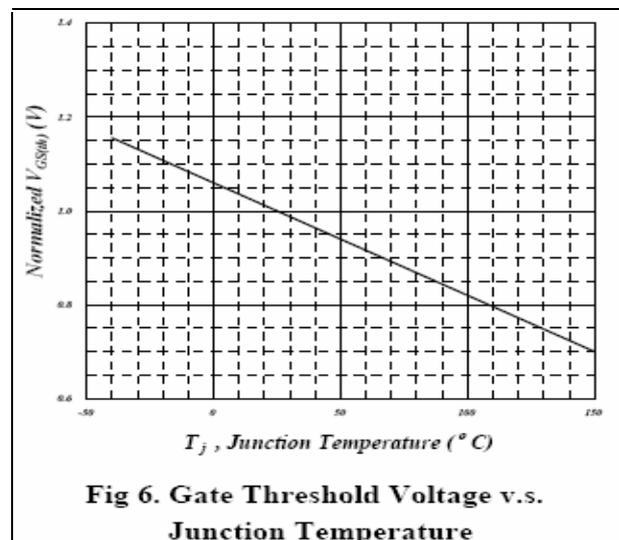


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

Characteristics Curve

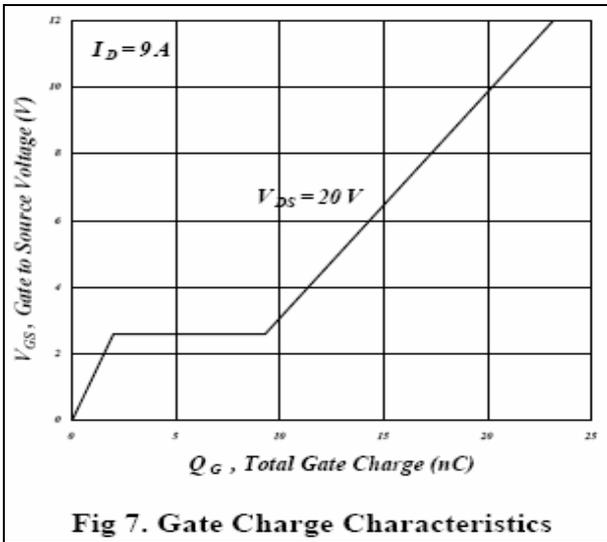


Fig 7. Gate Charge Characteristics

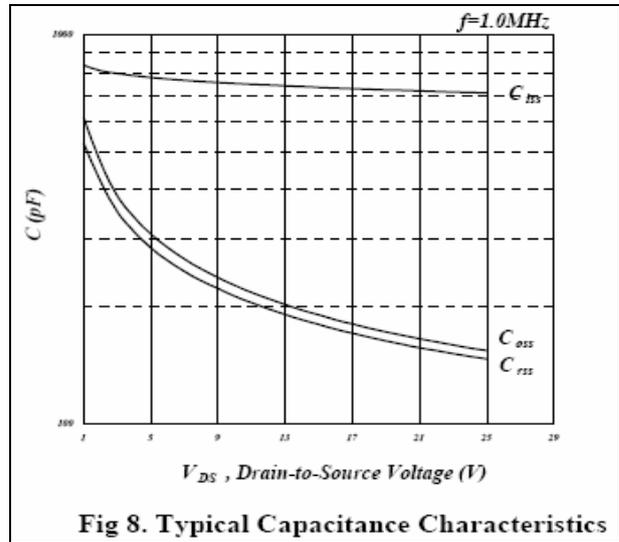


Fig 8. Typical Capacitance Characteristics

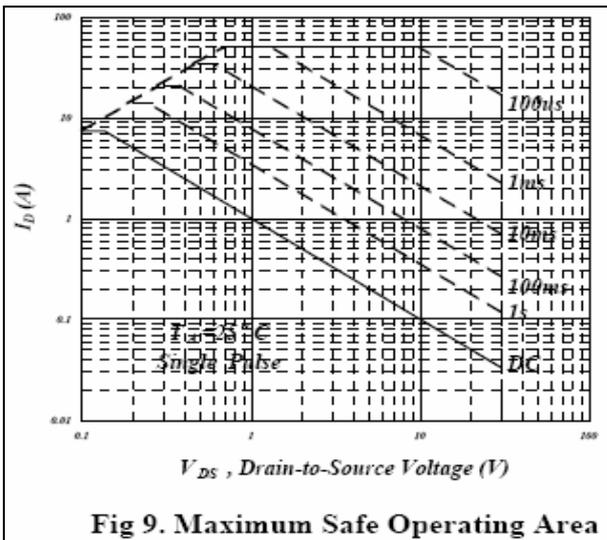


Fig 9. Maximum Safe Operating Area

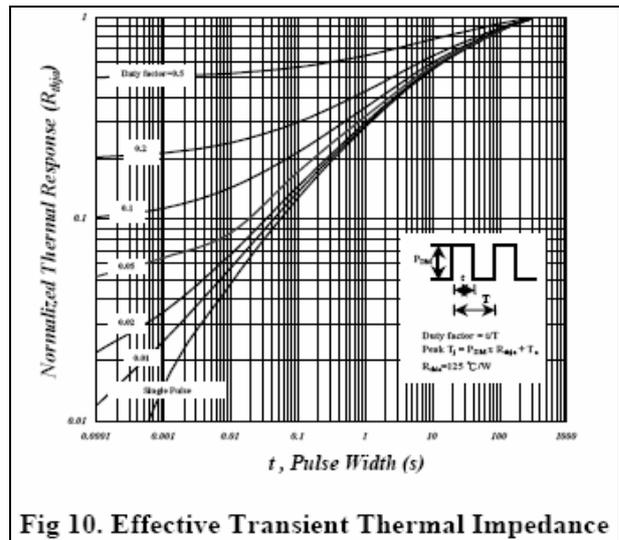


Fig 10. Effective Transient Thermal Impedance

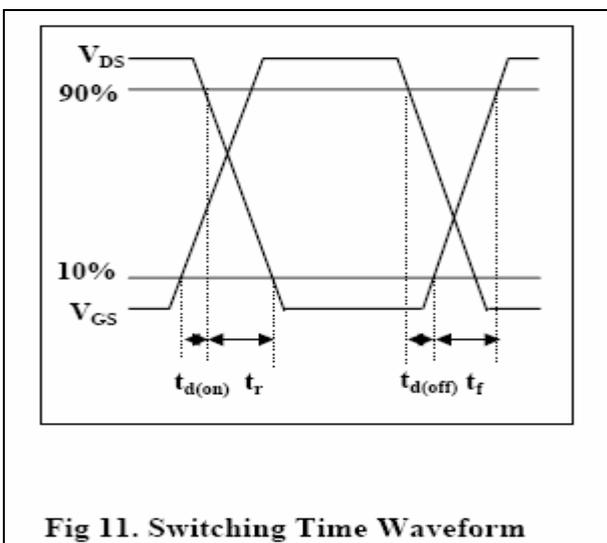


Fig 11. Switching Time Waveform

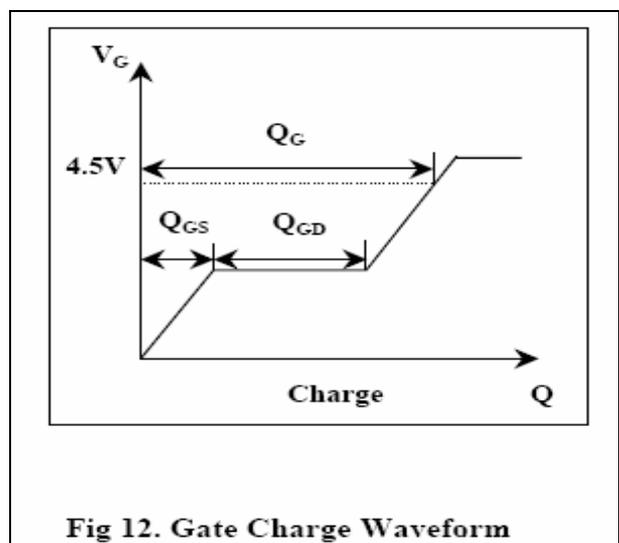
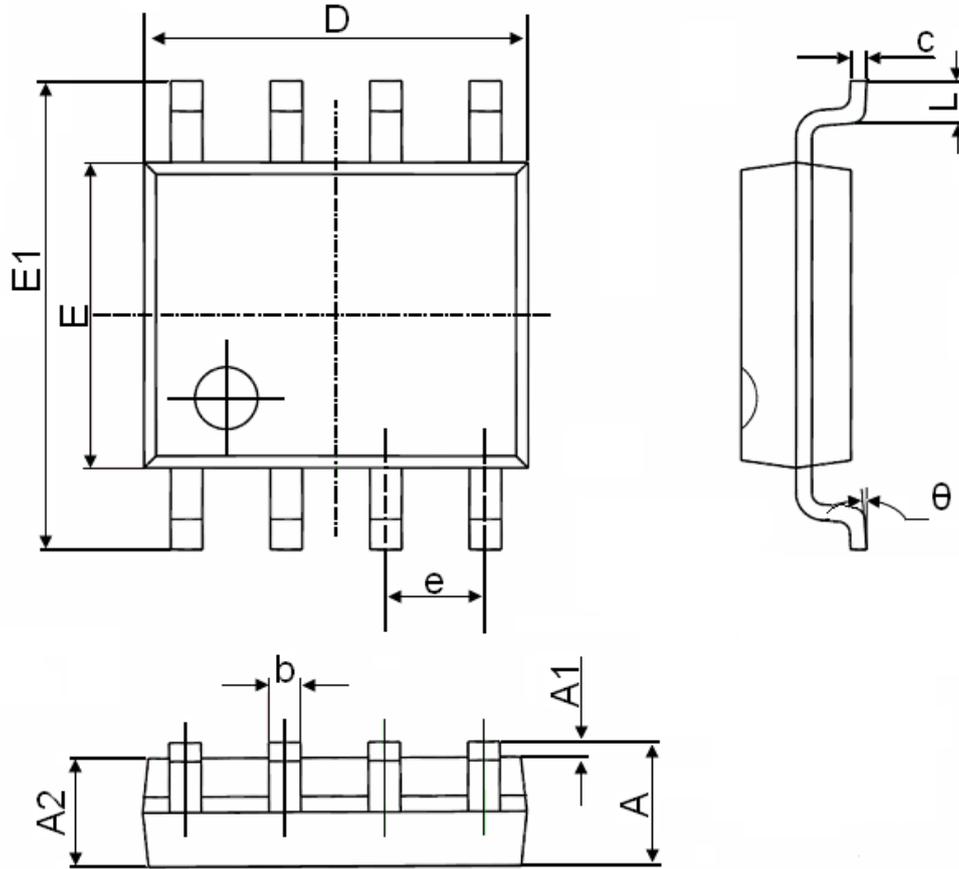


Fig 12. Gate Charge Waveform

SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°